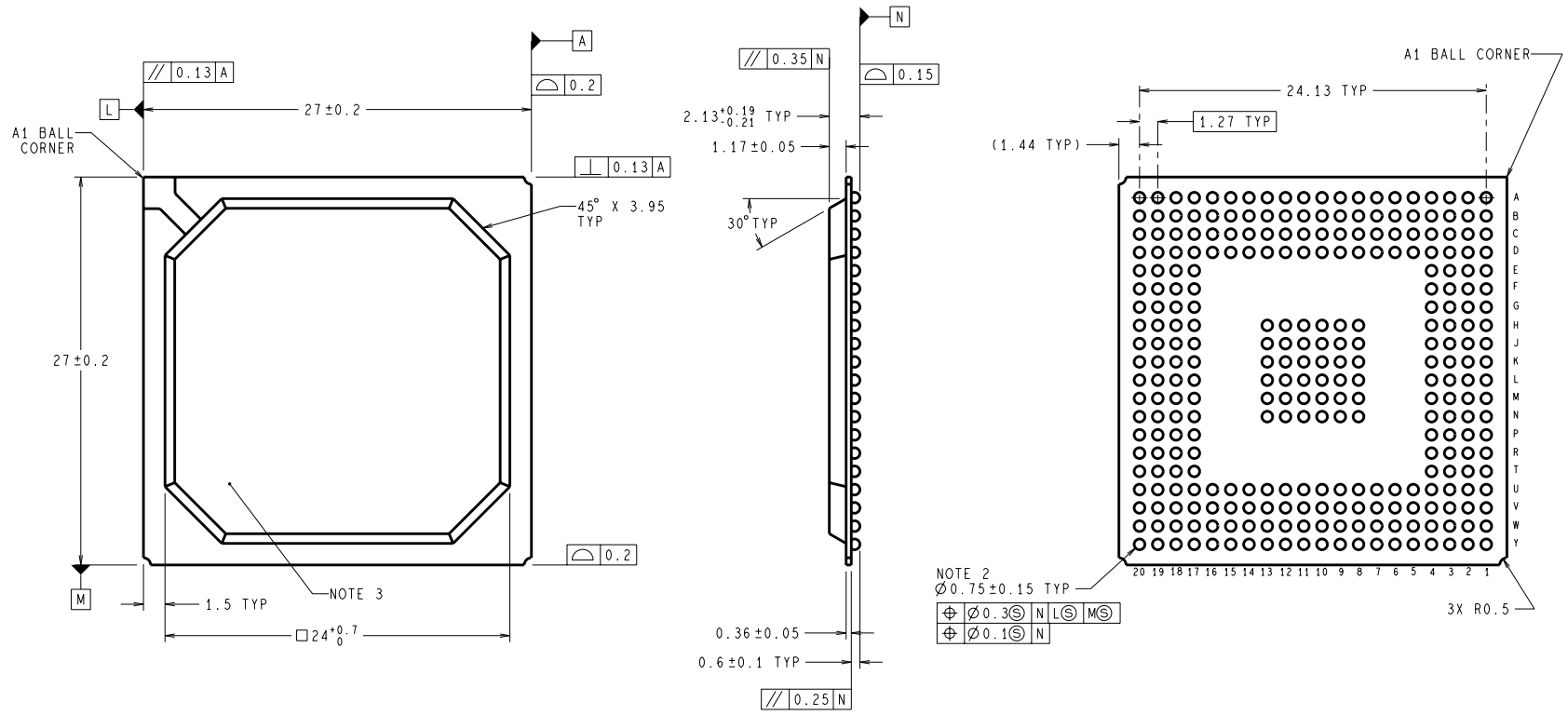


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11513	08/05/1996	TL/



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
2. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
3. THE MOLD SURFACE AREA MAY INCLUDE DIMPLE FOR A1 BALL CORNER IDENTIFICATION.
4. REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.27 PITCH, DATED NOV. 1993.
5. REFERENCE ANAM DRAWING 71242, DATED 3/18/1996.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN T. LEQUANG		08/05/1996			
DFTG. CHK.				PBGA, 27.0 X 27.0 X 2.13mm, 292 BALL, 1.27mm PITCH	
ENGR. CHK.					
 PROJECTION 1/8" (1MM)		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	MKT-UBE292A	A
DO NOT SCALE DRAWING				SHEET 1 of 1	